

Film Capacitors

EMI Suppression Capacitors (MKP)

Series/Type: B32911 ... B32916

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X1 / 330 V AC

Typical applications

- X1 class for interference suppression
- "Across the line" applications
- For apparatus permanently connected to mains and isolated from direct contact with humidity

Climatic

- Max. operating temperature: 110 °C
- Climatic category (IEC 60068-1): 40/110/56

Construction

- Dielectric: polypropylene (MKP)
- Plastic case (UL 94 V-0)
- Epoxy resin sealing (UL 94 V-0)

Features

- Verv small dimensions
- Good self-healing properties
- High voltage capability
- RoHS-compatible
- Halogen-free capacitors available on request

Terminals

- Parallel wire leads, lead-free tinned
- Special lead lengths available on request

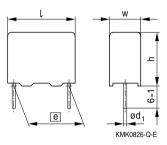
Marking

Manufacturer's logo, lot number, date code, rated capacitance (coded), capacitance tolerance (code letter), rated AC voltage (IEC), series number, sub-class (X1), dielectric code (MKP), climatic category, passive flammability category, approvals.

Delivery mode

Bulk (untaped)
Taped (Ammo pack or reel)
For taping details, refer to chapter
"Taping and packing".

Dimensional drawing



Dimensions in mm

Lead spacing ±0.4	Lead diameter d ₁	Туре
10	0.6	B32911
15 27.5	0.8	B32912 B32914
37.5	1.0	B32916

Marking examples

e =10 mm



KMK1261-Z

 $15 \le \theta \le 27.5 \text{ mm}$ ($C_R \le 1 \mu F$)



KMK1262-P

 $22.5 \le \underline{\theta} \le 37.5 \text{ mm}$ ($C_R > 1 \mu F$)



KMK1263-7



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Approvals

Approval marks	Standards	Certificate
W 10	EN 60384-14 / IEC 60384-14 (330 V AC)	40032766
71	UL1414 (250 V AC) UL1283 (300 V AC)	E97863 E157153
c AL 1)	CSA C22.2 No. 1 (250 V AC) CSA C22.2 No. 8 (300 V AC)	E97863 E157153

¹⁾ approved by UL

Overview of available types

					_
Lead spacing	10 mm	15 mm	22.5 mm	27.5 mm	37.5 mm
Type	B32911	B32912	B32913	B32914	B32916
C _R (μF)					
0.010					
0.022					
0.033					
0.047					
0.068					
0.10					
0.15					
0.22					
0.33					
0.47					
0.68					
1.0					
1.5					
2.2					
3.3					
4.7					
6.8					





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Ordering codes and packing units

Lead spacing	C _R	Max. dimensions	Ordering code	Ammo	Reel	Untaped
		$w \times h \times I$	(composition see	pack		
mm	μF	mm	below)	pcs./MOQ	pcs./MOQ	pcs./MOQ
10	0.010	4.0 × 9.0 × 13.0	B32911A3103+***	4000	6800	4000
	0.022	$5.0 \times 11.0 \times 13.0$	B32911B3223+***	3320	5200	4000
	0.033	$6.0\times12.0\times13.0$	B32911A3333M***	2720	4400	4000
15	0.022	$5.0\times10.5\times18.0$	B32912A3223+***	4680	5200	4000
	0.033	$5.0 \times 10.5 \times 18.0$	B32912A3333+***	4680	5200	4000
	0.047	$5.0 \times 10.5 \times 18.0$	B32912A3473+***	4680	5200	4000
	0.068	$6.0 \times 11.0 \times 18.0$	B32912A3683+***	3840	4400	4000
	0.10	$7.0 \times 12.5 \times 18.0$	B32912A3104+***	3320	3600	4000
	0.15	$7.0 \times 12.5 \times 18.0$	B32912B3154M***	3320	3600	4000
	0.15	$8.5 \times 14.5 \times 18.0$	B32912A3154+***	2720	2800	2000
	0.22	$8.5 \times 14.5 \times 18.0$	B32912B3224M***	2720	2800	2000
	0.22	$9.0 \times 17.5 \times 18.0$	B32912A3224+***	2560	2800	2000
	0.33	$9.0 \times 17.5 \times 18.0$	B32912B3334M***	2560	2800	2000
22.5	0.15	$6.0\times15.0\times26.5$	B32913A3154+***	2720	2800	2880
	0.22	$7.0\times16.0\times26.5$	B32913A3224+***	2320	2400	2520
	0.33	$8.5\times16.5\times26.5$	B32913A3334M***	1920	2000	2040
	0.47	$10.5\times18.5\times26.5$	B32913A3474M***	1560	1600	2160
27.5	0.47	$11.0 \times 21.0 \times 31.5$	B32914A3474+***	-	1400	1280
	0.68	$11.0 \times 21.0 \times 31.5$	B32914B3684+***	_	1400	1280
	1.0	$13.5 \times 23.0 \times 31.5$	B32914A3105+***	_	1000	1040
	1.5	$18.0 \times 27.5 \times 31.5$	B32914A3155+***	_	_	800
	2.2	$19.0\times30.0\times31.5$	B32914A3225M***	-	_	720
37.5	3.3	$18.0\times32.5\times41.5$	B32916A3335M***	_	_	720
	4.7	$20.0\times39.5\times41.5$	B32916A3475M***	_	_	640
	6.8	$28.0\times42.5\times41.5$	B32916A3685M***	_	_	440

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further intermediate capacitance values on request.

Composition of ordering code

+ = Capacitance tolerance code:

 $M = \pm 20\%$

 $K = \pm 10\%$

*** = Packaging code:

289 = Ammo pack

189 = Reel

000 = Untaped (lead length 6 - 1 mm)



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Technical data

Rated AC voltage (IEC 60384-14)	330 V (50/60 Hz)			
Maximum continuous DC voltage V _{DC}	760 \	/		
Max. operating temperature T _{op,max}	+110	°C		
DC test voltage	2500	V, 2 s		
Dissipation factor tan δ (in 10 ⁻³)			$C_{\text{R}} \leq 2.2~\mu\text{F}$	C _R > 2.2 μF
at 20 °C (upper limit values)	at	1 kHz	1	2
Insulation resistance R _{ins}		$C_R \le 0.33~\mu F$		$C_R > 0.33 \mu F$
or time constant $\tau = C_R \cdot R_{ins}$	100 0	000 MΩ		30 000 s
at 100 V DC, 20 °C,				
rel. humidity ≤ 65% and for 60 s				
(minimum as-delivered values)				
Passive flammability category	В			
to IEC 40 (CO) 752				
Capacitance tolerances		•		
(measured at 1 kHz)		±10% (K), ±20% (M)		

Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in $V/\mu s$.

" k_0 " represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in $V^2/\mu s$.

Note.

The values of dV/dt and k_0 provided below must not be exceeded in order to avoid damaging the capacitor.

dV/dt and k₀ values

Lead spacing	10 mm	15 mm	22.5 mm	27.5 mm	37.5 mm
dV/dt in V/μs	550	400	200	150	100
k_0 in $V^2/\mu s$	473 000	344 000	172 000	129 000	86 000





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Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

1.2 Resistance to soldering heat

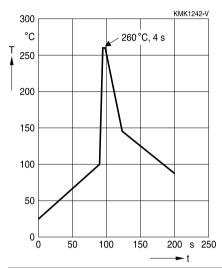
Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1A. Conditions:

Series	S	Solder bath temperature	Soldering time
MKT	boxed (except $2.5 \times 6.5 \times 7.2$ mm)	260 ±5 °C	10 ±1 s
	coated		
	uncoated (lead spacing > 10 mm)		
MFP			
MKP	(lead spacing > 7.5 mm)		
MKT	boxed (case $2.5 \times 6.5 \times 7.2$ mm)		5 ±1 s
MKP	(lead spacing ≤ 7.5 mm)		< 4 s
MKT	uncoated (lead spacing ≤ 10 mm)		recommended soldering
	insulated (B32559)		profile for MKT uncoated
			(lead spacing ≤ 10 mm) and
			insulated (B32559)



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Immersion depth	2.0 +0/-0.5 mm from capacitor body or seating plane	
Shield	Heat-absorbing board, (1.5 $\pm 0.5)$ mm thick, between capacitor body and liquid solder	
Evaluation criteria:		
Visual inspection	No visible damage	
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors	
tan δ	As specified in sectional specification	





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1.3 General notes on soldering

Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max} . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics: diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

EPCOS recommends the following conditions:

- Pre-heating with a maximum temperature of 110 °C
- Temperature inside the capacitor should not exceed the following limits:
 - MKP/MFP 110 °C
 - MKT 160 °C
- When SMD components are used together with leaded ones, the leaded film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.
- Leaded film capacitors are not suitable for reflow soldering.

Uncoated capacitors

For uncoated MKT capacitors with lead spacings ≤10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering



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Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6. EPCOS offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"





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Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"

Design of EMI Capacitors

EPCOS EMI capacitors use polypropylene (PP) film metalized with a thin layer of Zinc (Zn). The following key points have made this design suitable to IEC/UL testing, holding a minimum size.

- Overvoltage AC capability with very high temperature Endurance test of IEC60384-14 (3rd edition, 2005-07) / UL60384-14 (1st edition, 2009-04) must be performed at 1.25 × V_R at maximum temperature, during 1000 hours, with a capacitance drift less than 10%.
- Higher breakdown voltage withstanding if compared to other film metallizations, like Aluminum. IEC60384-14 (3rd edition, 2005-07) / UL60384-14 (1st edition, 2009-04) establishes high voltage tests performed at 4.3 × V_R −1 minute, impulse testing at 2500 V for C= 1 μF and active flammability tests.
- Damp heat steady state: 40 °C/ 93% RH / 56 days. (without voltage or current load)

Effect of humidity on capacitance stability

Long contact of a film capacitor with humidity can produce irreversible effects. Direct contact with liquid water or excess exposure to high ambient humidity or dew will eventually remove the film metallization and thus destroy the capacitor. Plastic boxed capacitors must be properly tested in the final application at the worst expected conditions of temperature and humidity in order to check if any parameter drift may provoke a circuit malfunction.

In case of penetration of humidity through the film, the layer of Zinc can be degraded, specially under AC operation (change of polarity), accelerated by the temperature, provoking an increment of the serial resistance of the electrode and eventually a reduction of the capacitance value. For DC operation, the parameter drift is much less.

Plastic boxes and resins can not protect 100% against humidity. Metal enclosures, resin potting or coatings or similar measures by customers in their applications will offer additional protection against humidity penetration.



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Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
$lpha_{ extsf{C}}$	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
Α	Capacitor surface area	Kondensatoroberfläche
β_{C}	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
С	Capacitance	Kapazität
C_R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
Δ C/C	Relative capacitance change (relative	Relative Kapazitätsänderung (relative
	deviation of actual value)	Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation	Kapazitätstoleranz (relative Abweichung
	from rated capacitance)	vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔT	Absolute temperature change	Absolute Temperaturänderung
	(self-heating)	(Selbsterwärmung)
$\Delta tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate	Differentielle Spannungsänderung
	of voltage rise)	(Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f ₁	Frequency limit for reducing permissible	Grenzfrequenz für thermisch bedingte
	AC voltage due to thermal limits	Reduzierung der zulässigen
		Wechselspannung
f_2	Frequency limit for reducing permissible	Grenzfrequenz für strombedingte
	AC voltage due to current limit	Reduzierung der zulässigen
,	5	Wechselspannung
f _r	Resonant frequency	Resonanzfrequenz
F_{D}	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur
_	Develop feeter	Diffusion
F _⊤	Derating factor	Deratingfaktor
1	Current (peak)	Stromspitze
I _C	Category current (max. continuous	Kategoriestrom (max. Dauerstrom)
-	current)	





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Symbol	English	German
I _{RMS}	(Sinusoidal) alternating current,	(Sinusförmiger) Wechselstrom
	root-mean-square value	
İz	Capacitance drift	Inkonstanz der Kapazität
k_0	Pulse characteristic	Impulskennwert
Ls	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λ_{o}	Constant failure rate during useful	Konstante Ausfallrate in der
	service life	Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des
		Entladekreises
R_{i}	Internal resistance	Innenwiderstand
R_{ins}	Insulation resistance	Isolationswiderstand
R_P	Parallel resistance	Parallelwiderstand
R_{s}	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
Т	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
$tan \; \delta_{\scriptscriptstyle D}$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ_P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ_s	Series component of dissipation factor	Serienanteil des Verlustfaktors
T_A	Ambient temperature	Umgebungstemperatur
T _{max}	Upper category temperature	Obere Kategorietemperatur
T_{min}	Lower category temperature	Untere Kategorietemperatur
t _{OL}	Operating life at operating temperature	Betriebszeit bei Betriebstemperatur und
OL.	and voltage	-spannung
T_{op}	Operating temperature	Beriebstemperatur
T _R	Rated temperature	Nenntemperatur
T_{ref}	Reference temperature	Referenztemperatur
t _{SL}	Reference service life	Referenz-Lebensdauer
V_{AC}	AC voltage	Wechselspannung



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Symbol	English	German
V_{c}	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige)
		Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V_{i}	Input voltage	Eingangsspannung
V_{\circ}	Output voltage	Ausgangssspannung
V_{op}	Operating voltage	Betriebsspannung
V_p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V_R	Rated voltage	Nennspannung
v̂ _R	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage,	(Sinusförmige) Wechselspannung
	root-mean-square value	
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung
		"Beschaltung"
Z	Impedance	Scheinwiderstand
е	Lead spacing	Rastermaß



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